

Title (en)
HETEROGENEOUS NESTED INTERPOSER PACKAGE FOR IC CHIPS

Title (de)
HETEROGENE VERSCHACHTELTE INTERPOSER-PACKUNG FÜR IC-CHIPS

Title (fr)
BOÎTIER D'INTERPOSEUR EMBOÎTÉ HÉTÉROGÈNE POUR PUCES DE CI

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Abstract (en)
Embodiments disclosed herein include electronic packages and methods of fabricating electronic packages. In an embodiment, an electronic package comprises an interposer, where a cavity passes through the interposer, and a nested component in the cavity. In an embodiment, the electronic package further comprises a die coupled to the interposer by a first interconnect and coupled to the nested component by a second interconnect. In an embodiment, the first and second interconnects comprise a first bump, a bump pad over the first bump, and a second bump over the bump pad.

IPC 8 full level
H01L 21/683 (2006.01)

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C-Set (source: EP)

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3. **H01L 2224/131 + H01L 2924/014 + H01L 2924/00014**

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EP 3751607 A1 20201216; CN 112071826 A 20201211; CN 117790482 A 20240329; EP 4181193 A1 20230517; EP 4325553 A2 20240221; EP 4325553 A3 20240522; KR 20200141921 A 20201221; KR 20240007894 A 20240117; SG 10202004327Q A 20210128; TW 202101692 A 20210101; TW 202418502 A 20240501; TW I829926 B 20240121; US 11735533 B2 20230822; US 11824018 B2 20231121; US 2020395313 A1 20201217; US 2023134049 A1 20230504; US 2024038687 A1 20240201; US 2024128205 A1 20240418

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